



Subject card

Subject name and code	Design Methodology and Manufacturing, PG_00048073						
Field of study	Electronics and Telecommunications						
Date of commencement of studies	October 2022	Academic year of realisation of subject				2024/2025	
Education level	first-cycle studies	Subject group				Optional subject group Subject group related to scientific research in the field of study	
Mode of study	Full-time studies	Mode of delivery				at the university	
Year of study	3	Language of instruction				Polish	
Semester of study	5	ECTS credits				1.0	
Learning profile	general academic profile	Assessment form				assessment	
Conducting unit	Department of Metrology and Optoelectronics -> Faculty of Electronics, Telecommunications and Informatics						
Name and surname of lecturer (lecturers)	Subject supervisor		dr inż. Arkadiusz Szewczyk				
	Teachers		dr inż. Arkadiusz Szewczyk				
Lesson types and methods of instruction	Lesson type	Lecture	Tutorial	Laboratory	Project	Seminar	SUM
	Number of study hours	15.0	0.0	0.0	0.0	0.0	15
	E-learning hours included: 0.0						
Learning activity and number of study hours	Learning activity	Participation in didactic classes included in study plan		Participation in consultation hours		Self-study	SUM
	Number of study hours	15		1.0		9.0	25
Subject objectives	Give the knowledge of technology of design and manufacturing of electronic equipment.						
Learning outcomes	Course outcome		Subject outcome		Method of verification		
	[K6_W32] Knows the parameters, functions and methods of analysis, design and optimization of analogue and digital circuits and electronic systems		knows how to choose and apply tools and techniques for designing electronic devices.		[SW1] Assessment of factual knowledge		
[K6_U03] can design, according to required specifications, and make a simple device, facility, system or carry out a process, specific to the field of study, using suitable methods, techniques, tools and materials, following engineering standards and norms, applying technologies specific to the field of study and experience gained in the professional engineering environment		is able to design, in accordance with the given specification, and build a simple electronic device		[SU1] Assessment of task fulfilment			
Subject contents	1. Basic problems of designing and engineering of electronic devices and systems. 2. Designing of electronic devices allowing requirements of manufacturing. 3. Factors determining designing and construction processes. Optimal solutions. 4. Enclosure and module systems. 5. Internal connections between modules: fixed and separable. 6. Elements with contacts; matching of modules. 7. Cabling. Parameters of cables, materials for conducting wires, isolators and shields. 8. Connection techniques: soldering, wire-wrapping, crimping. 9. Manual and automatic soldering. 10. Influence of the electronic devices mounting technology on environment; lead-free soldering, flux materials. 11. Electronic components for through-hole and surface mounting technology. 12. Surface mounting technology. Wave soldering, reflow soldering. 13. Production units for automatic mounting of electronic components. Automatic units for components positioning, for depositing of glue and solder. 14. Designing of pads. Influence of the mounting technology on printed board design. 15. Construction and techniques of printed circuit boards manufacturing. 16. Electronic Design Automation (EDA) software. 17. Preparation of fabrication documentation. 18. Grounding and shielding techniques. Designing of shields. 19. Cooling systems in electronic devices. Designing of the cooling systems and radiators for the typical power components.						
Prerequisites and co-requisites	No requirements						
Assessment methods and criteria	Subject passing criteria		Passing threshold		Percentage of the final grade		
	Writing exam		50.0%		100.0%		

Recommended reading	Basic literature	Ryszard Kisiel: "Podstawy technologii montażu dla elektroników", BTC 2012
	Supplementary literature	Krystyna Bukart, Halina Hackiewicz: "Lutowanie bezołowiowe", BTC 2007
	eResources addresses	
Example issues/ example questions/ tasks being completed	CAD software, soldering, PCB assembly, devices outlines, connections, grounding, shielding.	
Work placement	Not applicable	